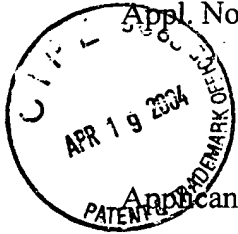


Appl. No. 09/802,664



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE

Application No.: 09/802,664

Filed: March 9, 2001

Title: **Flip chip interconnection structure**

)
) Examiner: Hsien Ming LEE
)
) Group Art Unit: 2823
)
) Date: April 13, 2004
)
)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on April 13, 2004.

Signed


Bill Kennedy

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office action mailed November 13, 2003, kindly amend the application as follows:

There are no claim amendments. The current status of the claims is reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.

An **Appendix A** and an **Appendix B**, each being a copy of a portion of a reference work, are enclosed behind the last page of the Remarks.